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Why Computational Electronics?

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Network for Computational Nanotechnology 

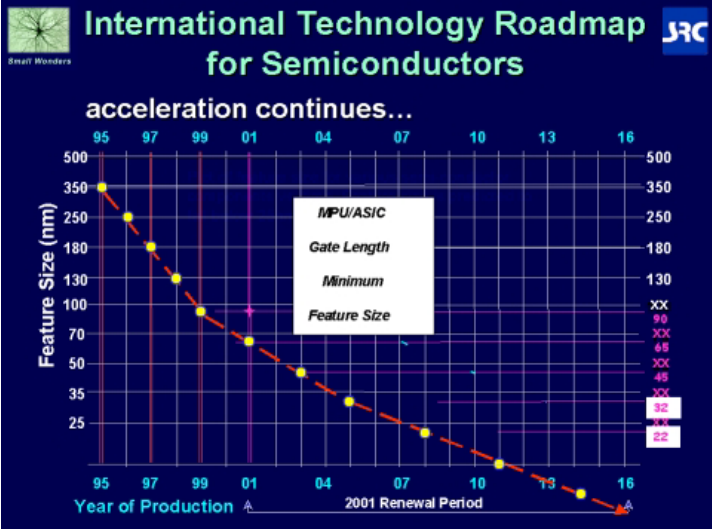
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Device Scaling




International Technology Roadmap for Semiconductors

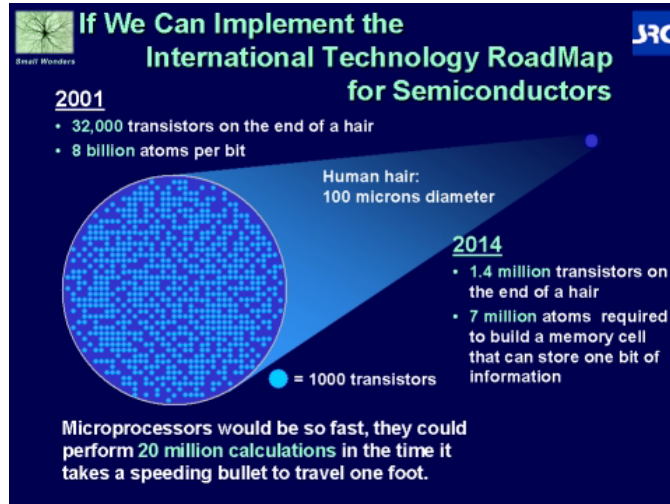
acceleration continues...



| Year | Feature Size (nm) |
|------|-------------------|
| 1995 | 350 |
| 1997 | 250 |
| 1999 | 180 |
| 2001 | 130 |
| 2004 | 90 |
| 2007 | 65 |
| 2010 | 45 |
| 2013 | 32 |
| 2016 | 22 |

Year of Production 2001 Renewal Period

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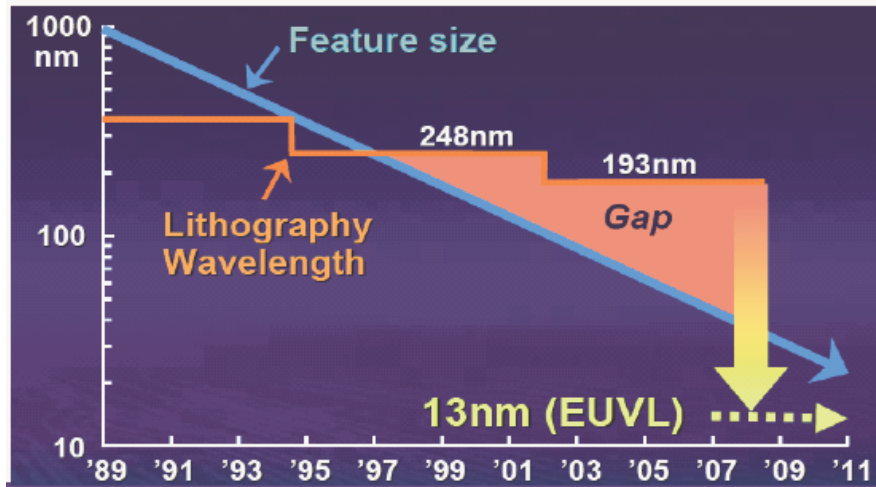
Approaching a "Red Brick Wall"

Challenges/Opportunities for Semiconductor R&D

| Year of Production: | 1999 | 2002 | 2005 | 2008 | 2011 | 2014 |
|------------------------------------|---------|---------|---------|---------|---------|---------|
| DRAM Half-Pitch [nm]: | 180 | 130 | 100 | 70 | 50 | 35 |
| Overlay Accuracy [nm]: | 65 | 45 | 35 | 25 | 20 | 15 |
| MPU Gate Length [nm]: | 140 | 85-90 | 65 | 45 | 30-32 | 20-22 |
| CD Control [nm]: | 14 | 9 | 6 | 4 | 3 | 2 |
| T _{ox} (equivalent) [nm]: | 1.9-2.5 | 1.5-1.9 | 1.0-1.5 | 0.8-1.2 | 0.6-0.8 | 0.5-0.6 |
| Junction Depth [nm]: | 42-70 | 25-43 | 20-33 | 16-26 | 11-19 | 8-13 |
| Metal Cladding [nm]: | 17 | 13 | 10 | 0 | 0 | 0 |
| Inter-Metal Dielectric K: | 3.5-4.0 | 2.7-3.5 | 1.6-2.2 | 1.5 | <1.5 | <1.5 |

1. Lithography Lags Device Scaling

- Extreme Ultraviolet Lithography (EUV) can close the gap



2. Isolation of Devices as Second Barrier

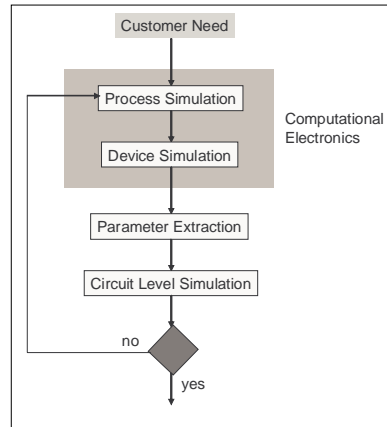
- Individual devices must be isolated to avoid unwanted interactions
- Formation of parasitic MOS channels must be avoided
 - Use a thin oxide for the transistor
 - Use a significantly thicker field oxide elsewhere
 - ✓ Thicker oxide increases the threshold voltage to a value above the supply voltage
 - ✓ Prevents a channel from being formed in the substrate under normal circumstances

| NON-CLASSICAL CMOS DEVICES | | | | | |
|----------------------------|--|---|---|--|------------------------|
| Device | Ultrathin Body SOI | Band-Engineered Transistor | Vertical Transistor | FinFET | Double-Gate Transistor |
| Concept | Fully-depleted SOI | SiGe or Strained Si Channel; bulk Si or SOI | Double-gate or surround-gate structure | | |
| Application/Driver | Higher performance, higher transistor density, lower power dissipation | | | | |
| Advantages | Improved subthreshold slope; V_T controllability | Higher drive current; compatible with bulk Si and SOI | Higher drive current; lithography independent gate length | Higher drive current; Improved subthreshold slope; improved short-channel effect (SCE); stacked NAND | |
| Scaling Issues | Si film thickness, gate stack; worse SCE than bulk CMOS | High mobility film thickness (SOI); gate stack; integratability | Si film thickness; gate stack; integratability; process complexity; accurate TCAD including quantum-mechanical (QM) effects | Gate alignment; Si film thickness; gate stack; integratability; process complexity; accurate TCAD | |
| Design Challenges | Device characterization; compact model and parameter extraction | Device characterization | Device characterization; PD versus FD; compact model and parameter extraction; applicability to mixed signal applications | | |

- As devices shrink into the nanometer scale, the trial and error approach is becoming more and more expensive
- As a result, the Computational Electronics have emerged as an important field in the device manufacturing process as it can offer:
 - The possibility to test hypothetical devices which has not yet been manufactured
 - Observation of phenomena that can not be measured on real devices

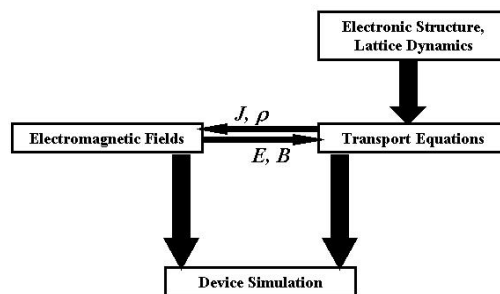
What is Computational Electronics?

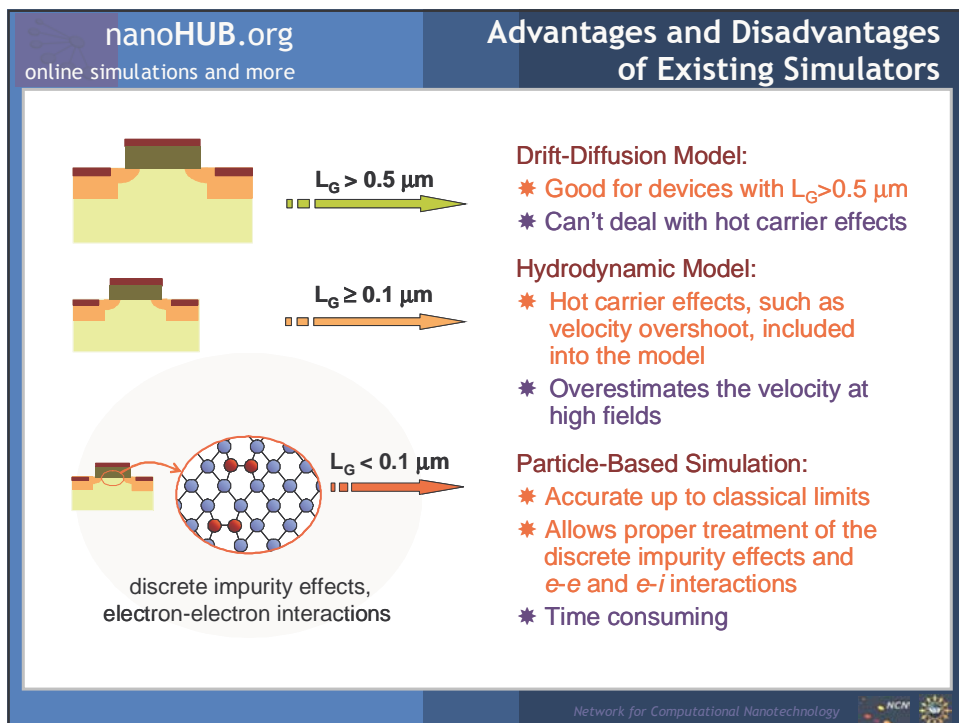
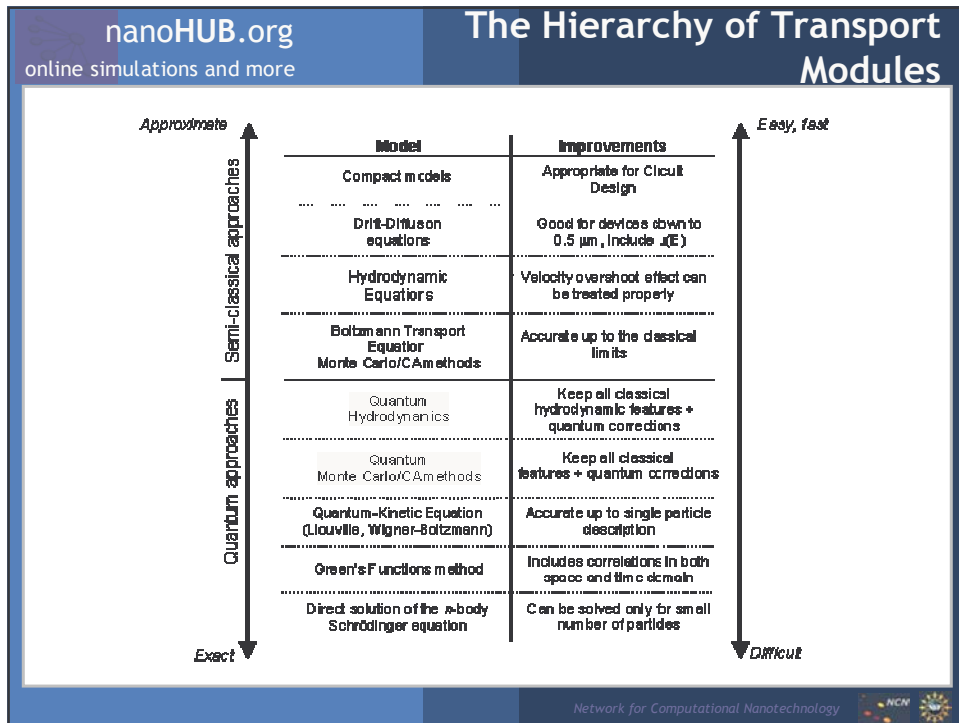
- Computational electronics is related to, but different from TCAD (technology for computer-aided design).
- The relationship between the various simulation design steps needed to achieve certain customer need is summarized on the figure.



Device Simulation Sequence

- There are two components to successful simulation of device properties and these include:
 - The bandstructure module
 - The transport module coupled to the electromagnetic fields solver
- The relationship between these components is summarized below





| | $L \ll l_{e-ph}$ | | | $L \sim l_{e-ph}$ | $L \gg l_{e-ph}$ |
|-------------------------------|--------------------------|----------------------|------------------------|-------------------|------------------|
| | $L < \lambda$ | $L < l_{e-e}$ | $L \gg l_{e-e}$ | | |
| Transport Regime | Quantum | Ballistic | Fluid | Fluid | Diffusive |
| Scattering | Rare | Rare | e-e (Many), e-ph (Few) | | Many |
| Model: | | | | | |
| Drift-Diffusion | | | | | |
| Hydrodynamic | | Quantum Hydrodynamic | | | |
| Monte Carlo | | | | | |
| Schrodinger/Green's Functions | Wave | | | | |
| Applications | Nanowires, Superlattices | Ballistic Transistor | Current IC's | Current IC's | Older IC's |

- 2D MOS:** MINIMOS, GEMINI, PISCES, CADDET, HFIELDS, CURRY, PADRE
- 3D MOS:** WATMOS, FIELDAY, MINIMOS3D, PADRE
- 1D BJT:** SEDAN, BIPOLE, LUSTRE
- 2D BJT:** BAMBI, CURRY, PADRE
- MESFETs:** CUPID
- MOS-Capacitors:** SCHRED